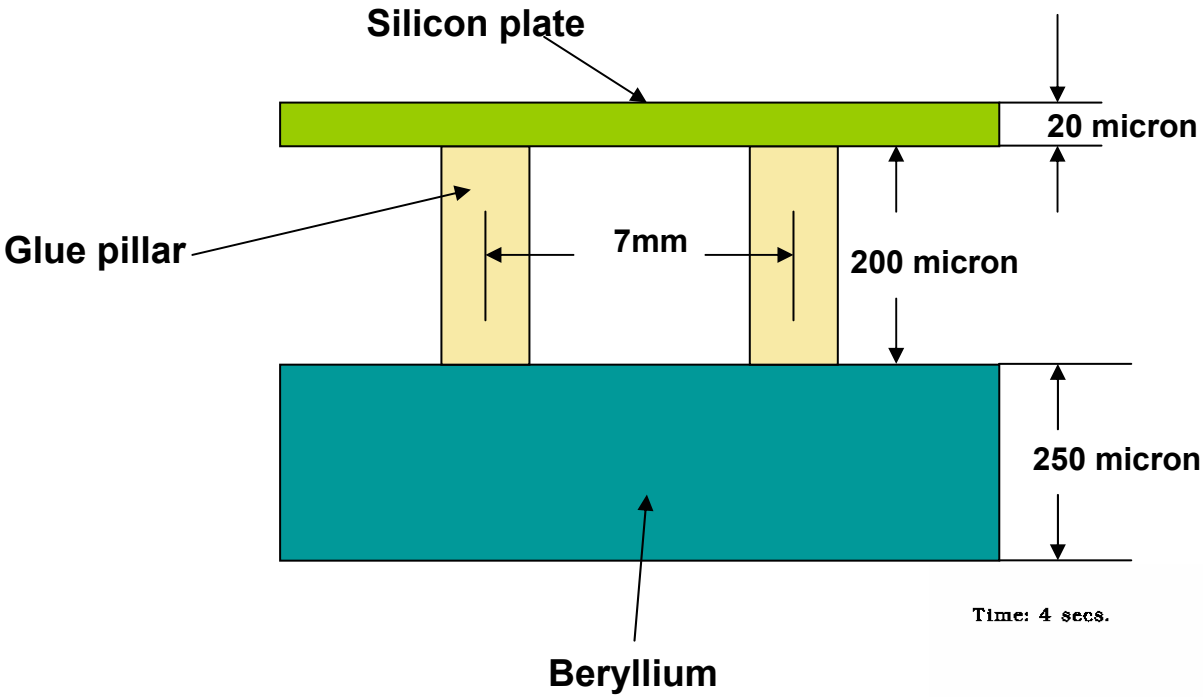
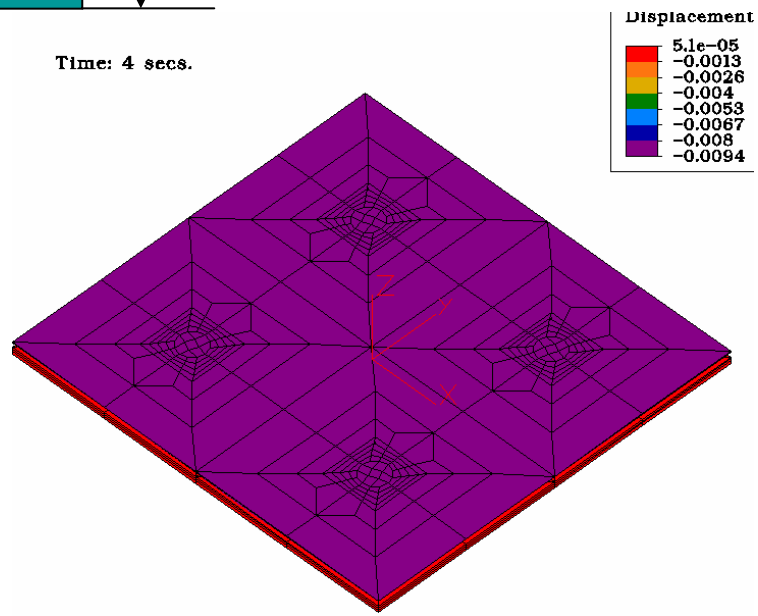
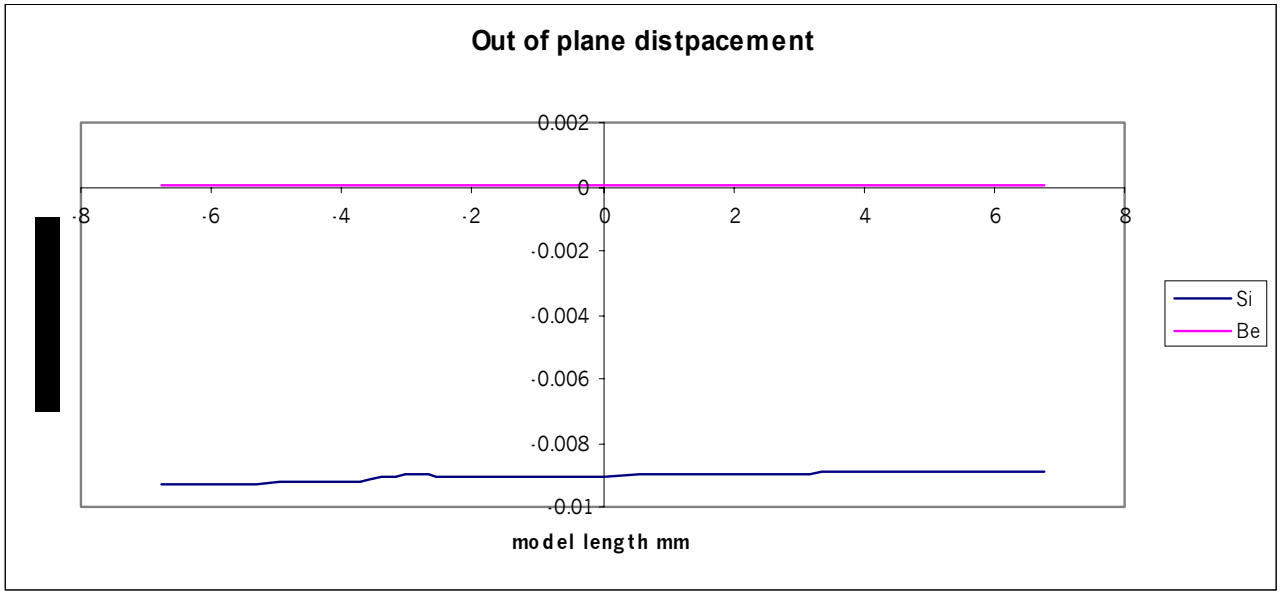
No well case pitch model





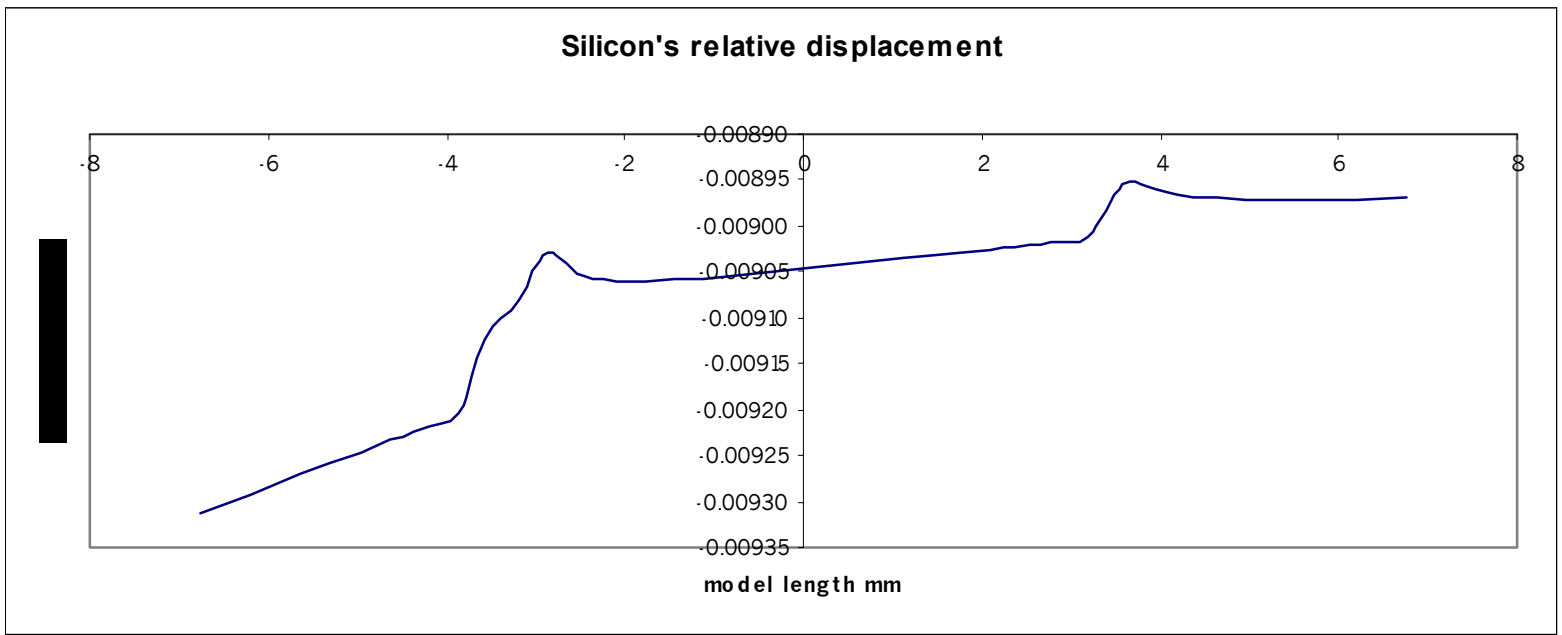


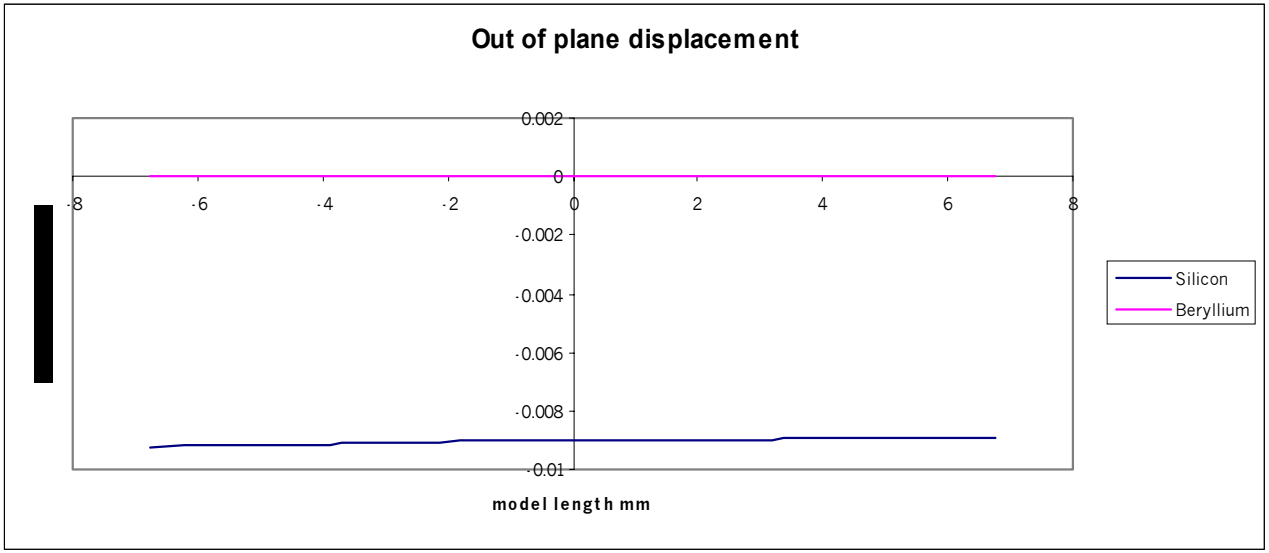
No well case (small pitch model) displacement plots(1)

Thickness of Silicon: **20 micron**

The height of glue: **200 micron**

The thickness of Beryllium: **250 micron**



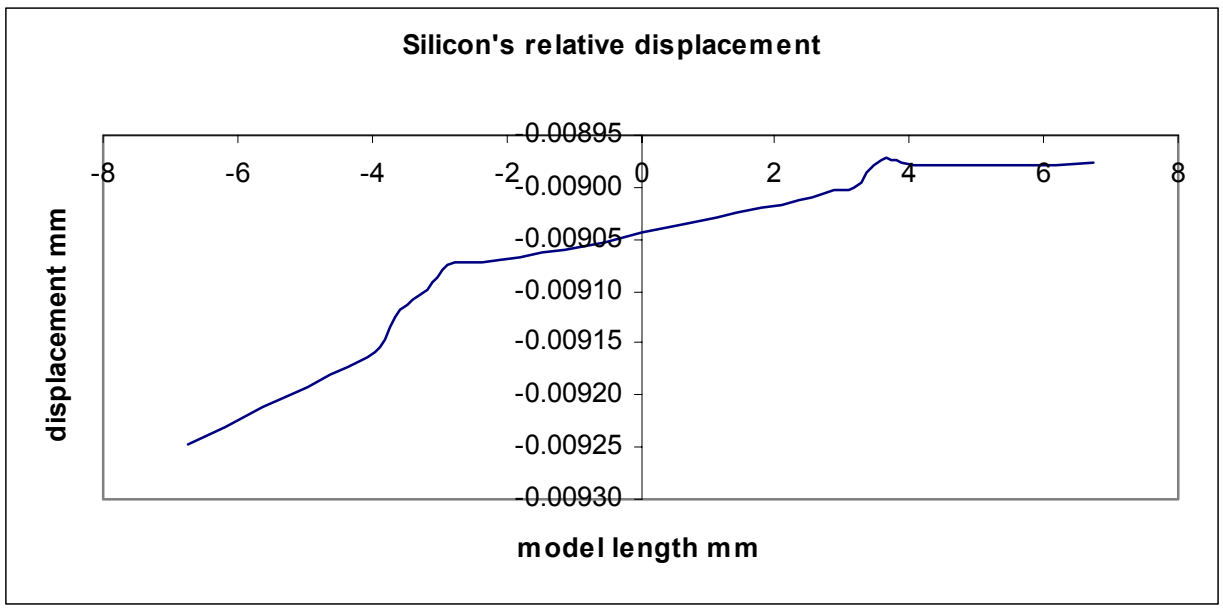


No well case (small pitch model) displacement plots(2)

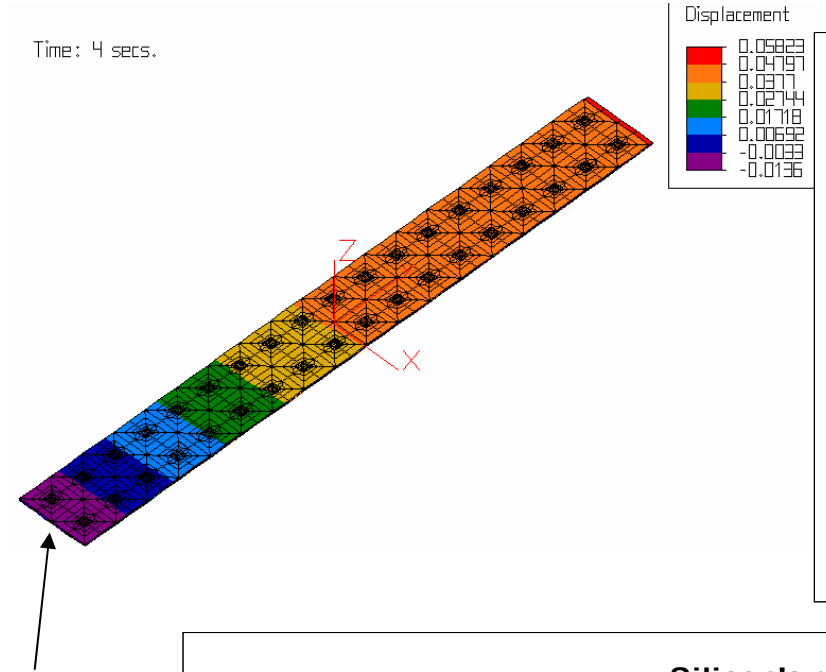
Thickness of Silicon: **40 micron**

The height of glue: **200 micron**

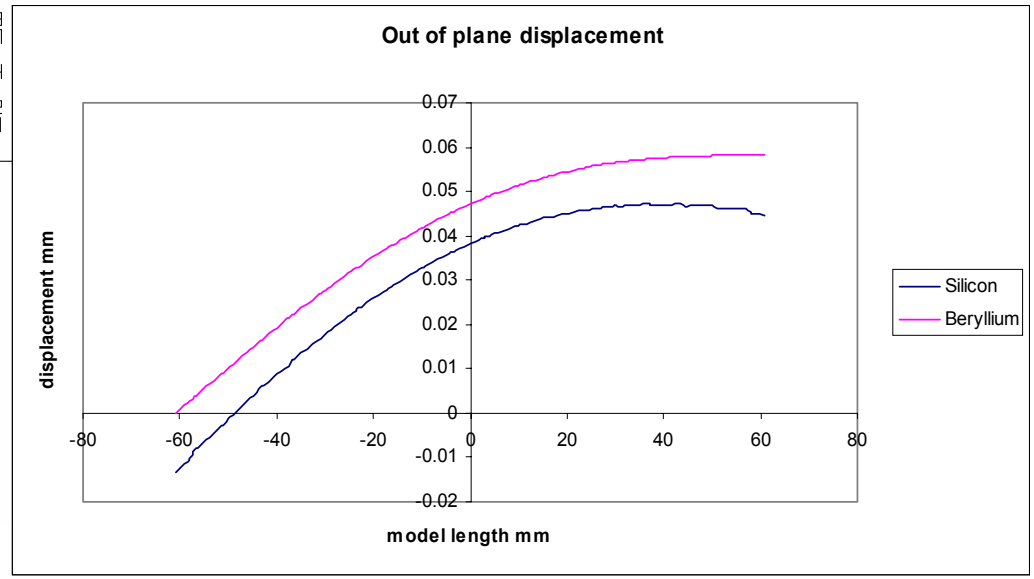
The thickness of Beryllium: **250 micron**

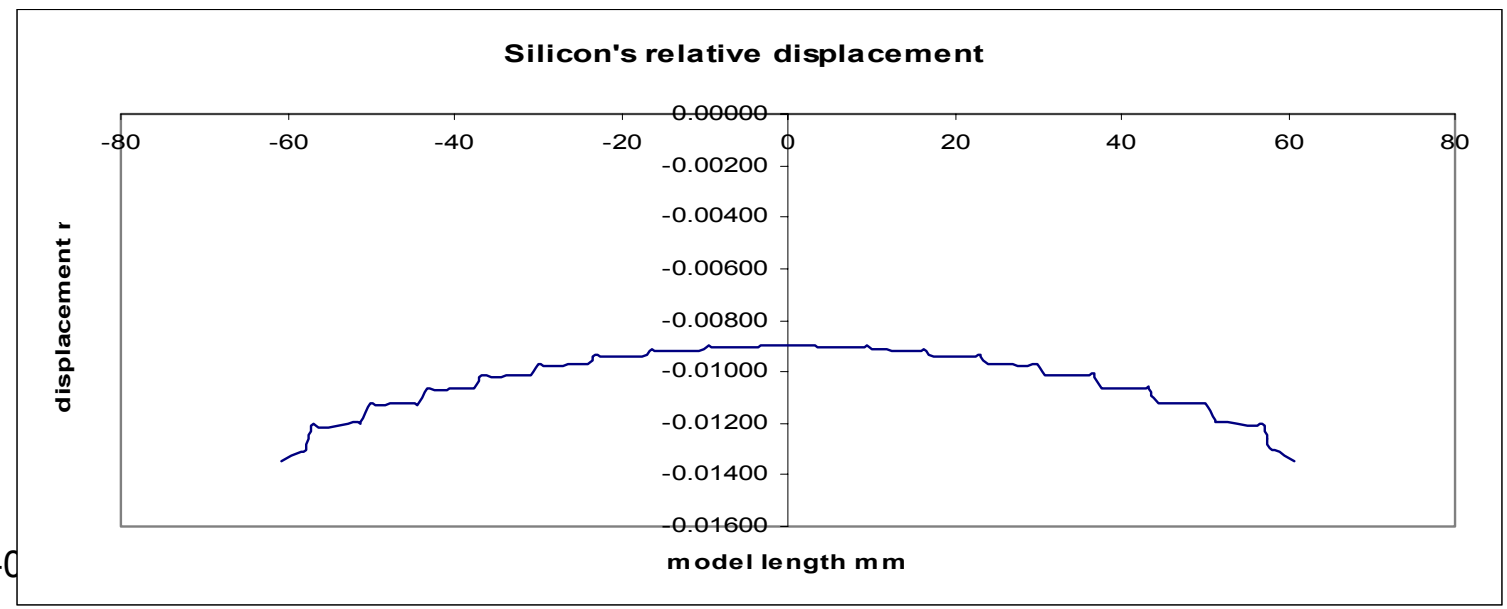


No well case ¼ model displacement plots (20micron thick Silicon)

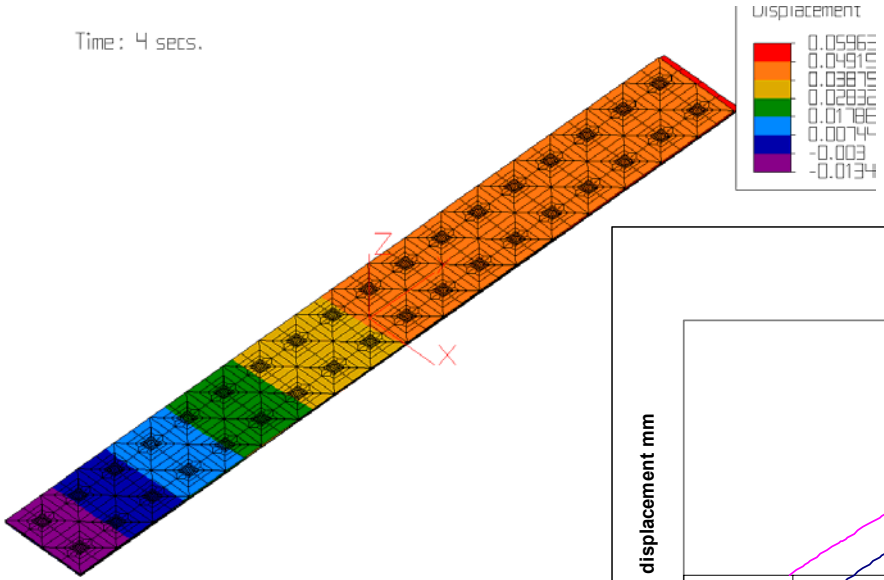


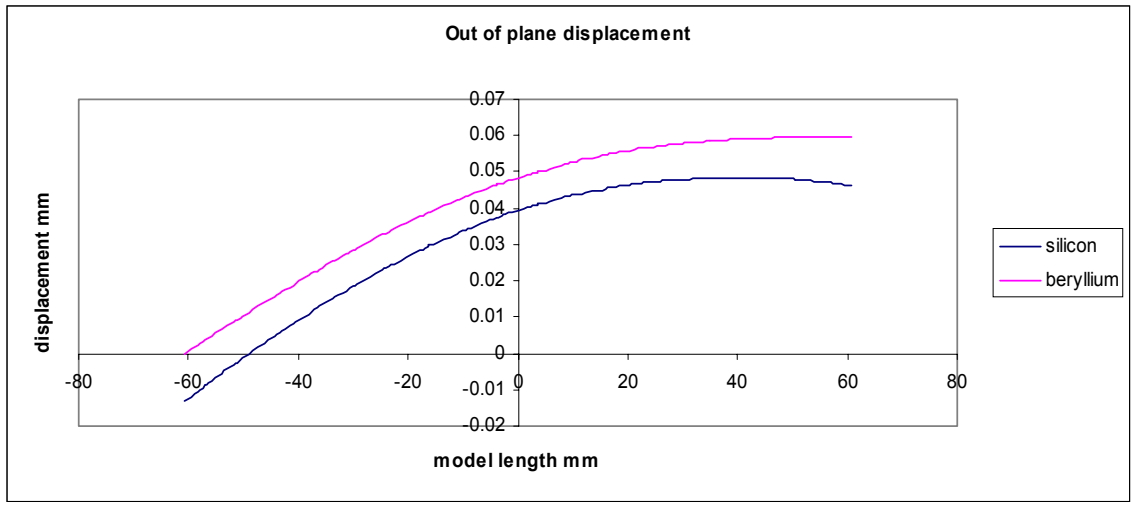
Simply supported

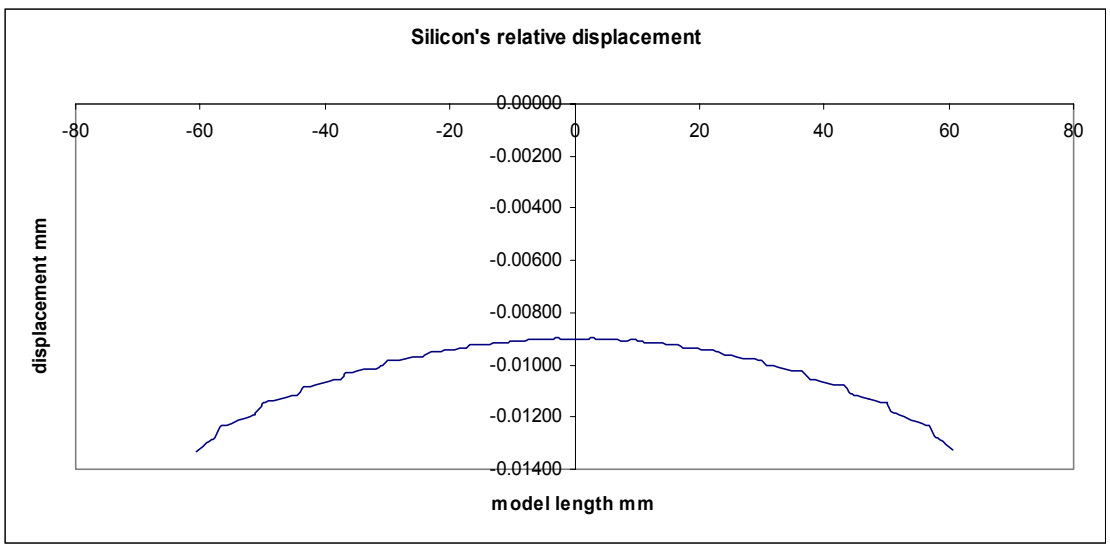




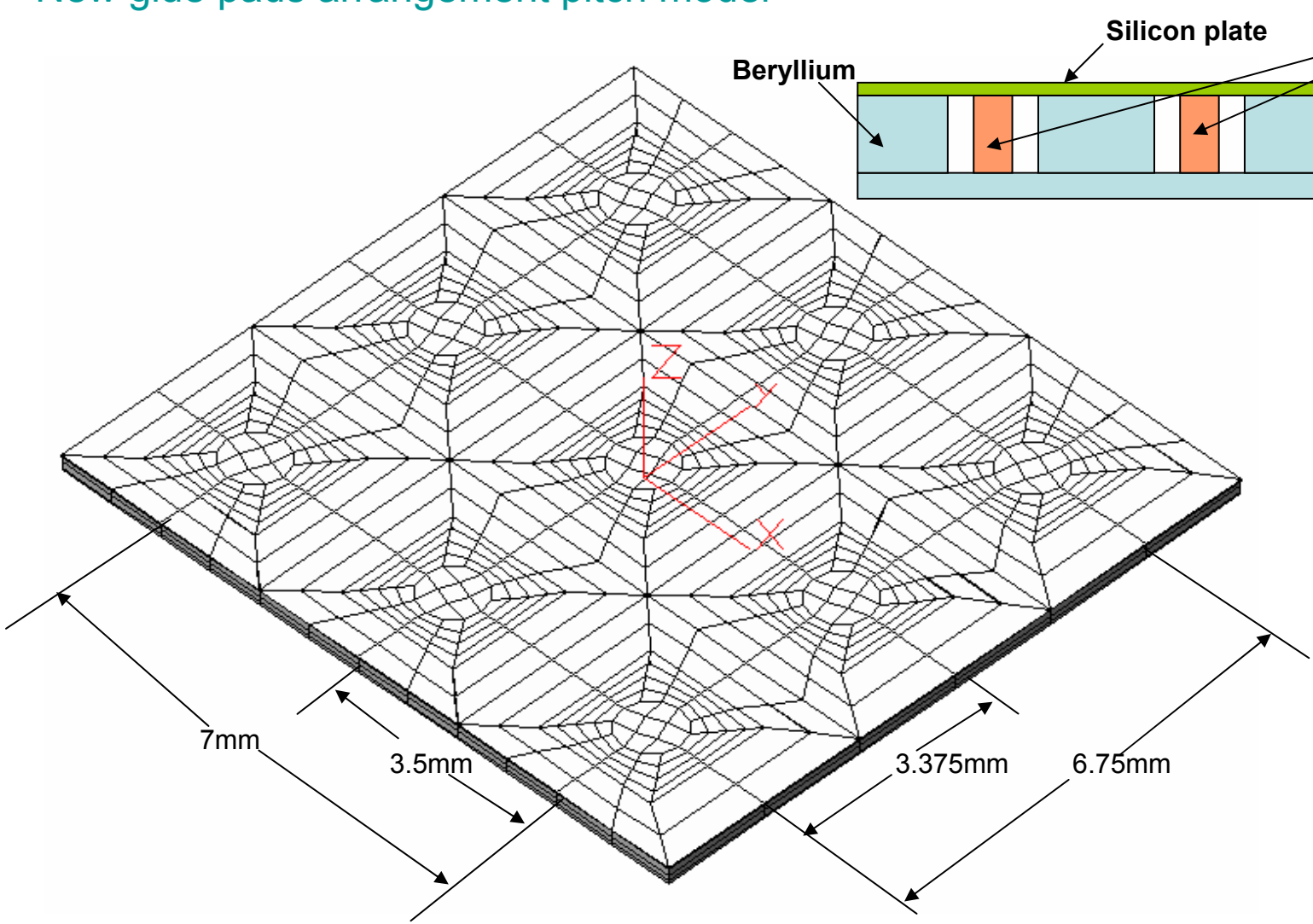
No well case ¼ model displacement plots (40micron thick Silicon)



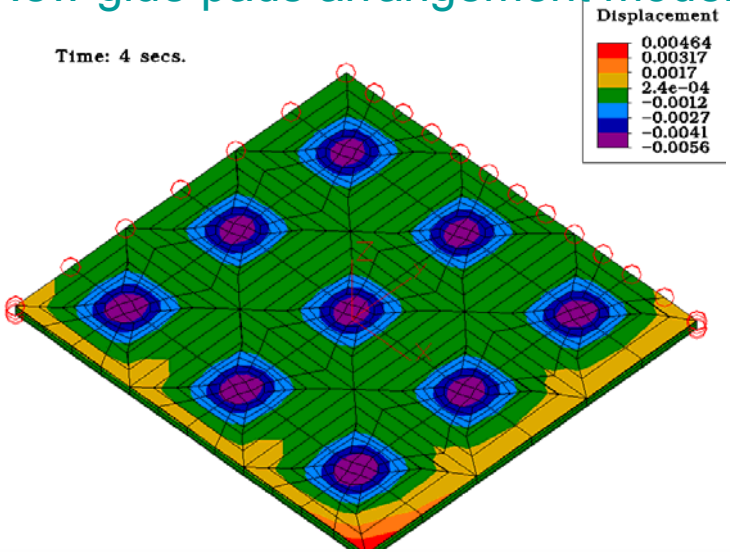


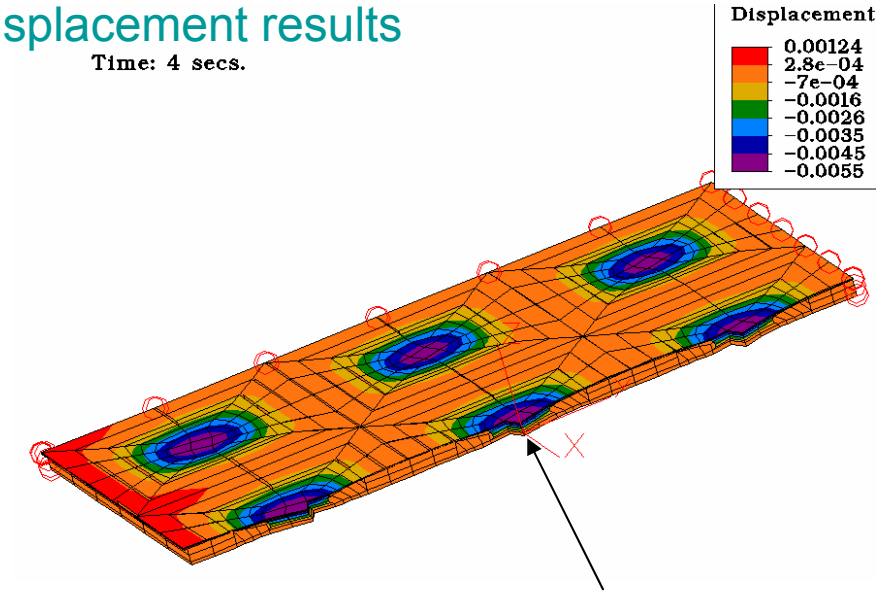


New glue pads arrangement pitch model

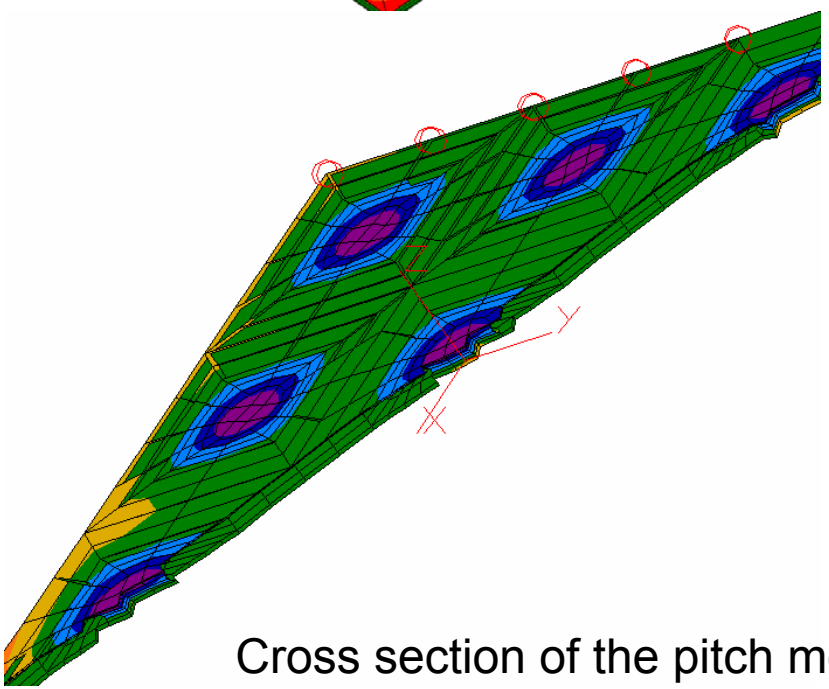


New glue pads arrangement model's displacement results

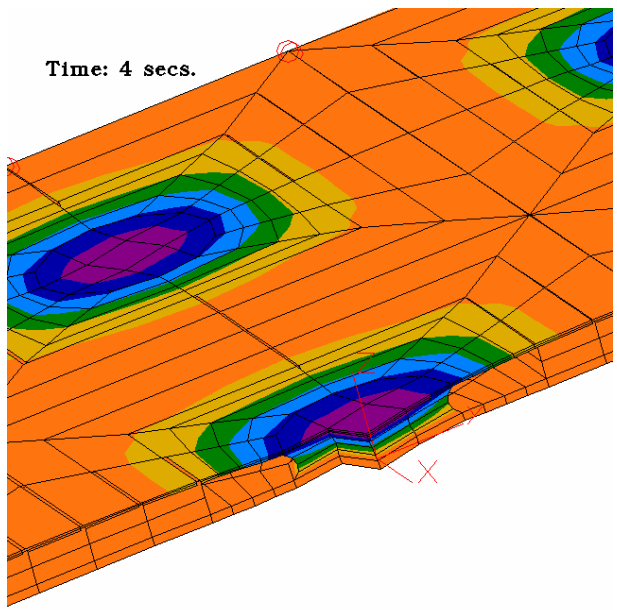


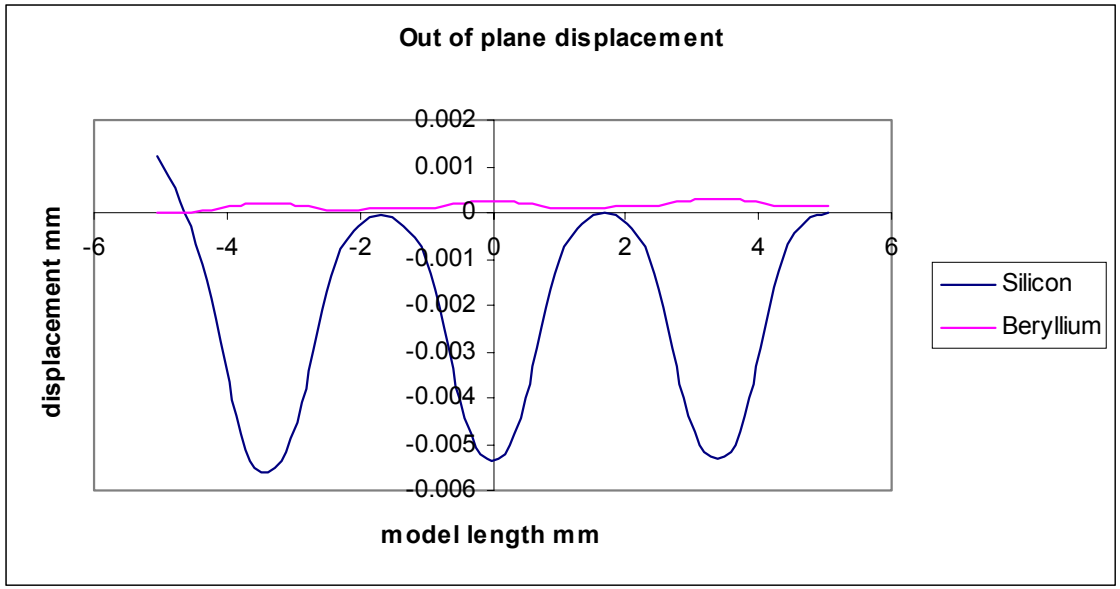


Zoom in glue pad

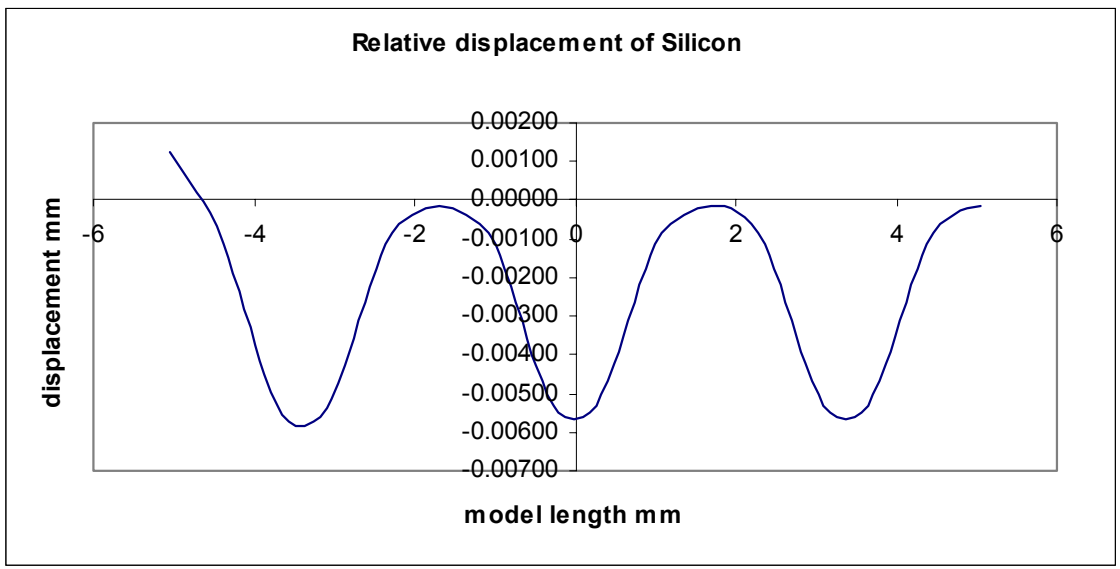


Cross section of the pitch model





New glue pads arrangement model's displacement plots

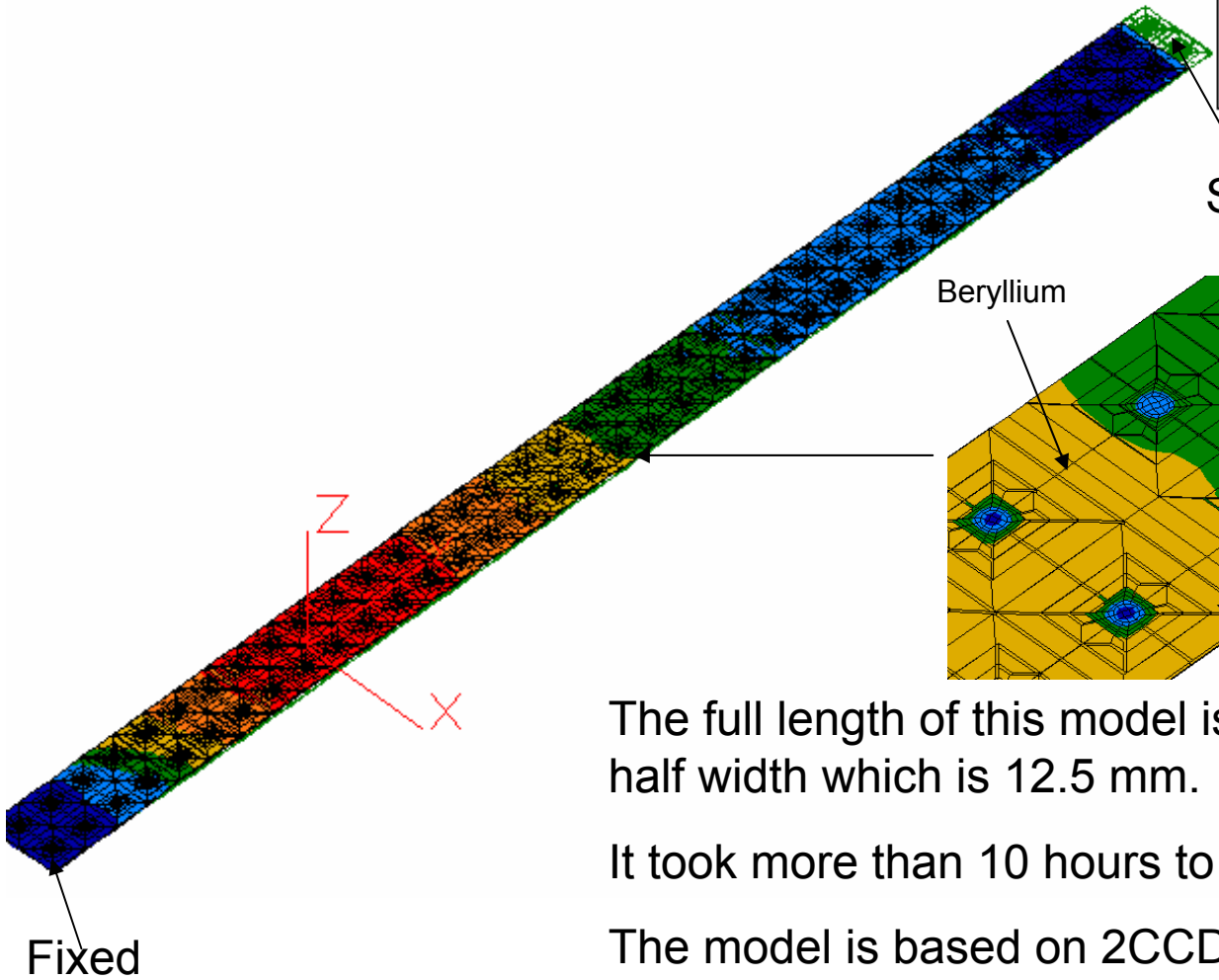


The distance between adhesive pads is 3.375mm

Standard support case model (with well)

Time: 4 secs.

Out of plane displacement plots of the standard support case (1)

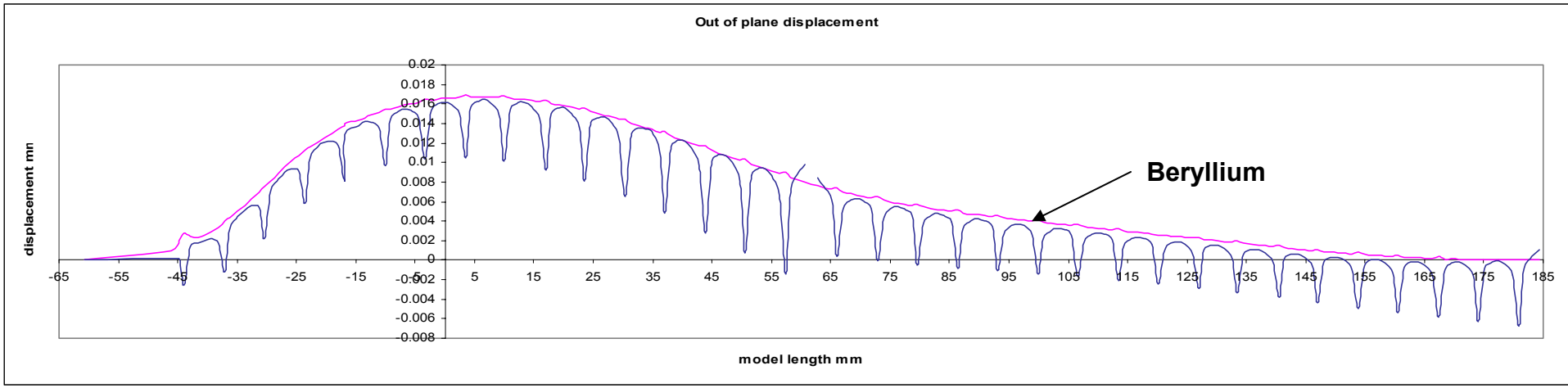


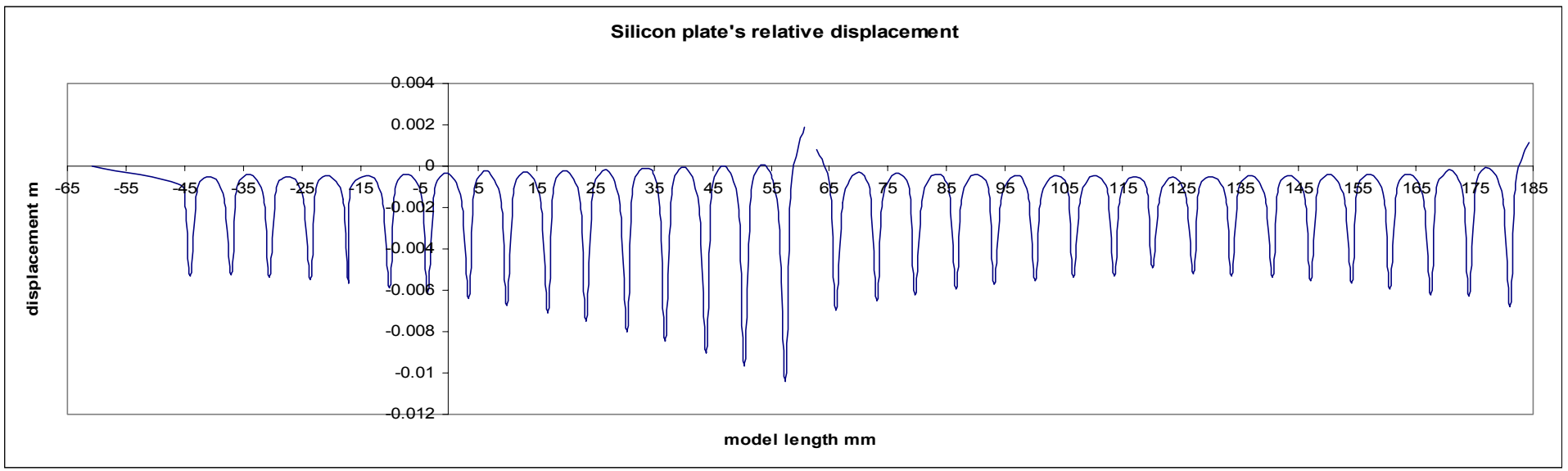
The full length of this model is 250 mm, half width which is 12.5 mm.

It took more than 10 hours to run.

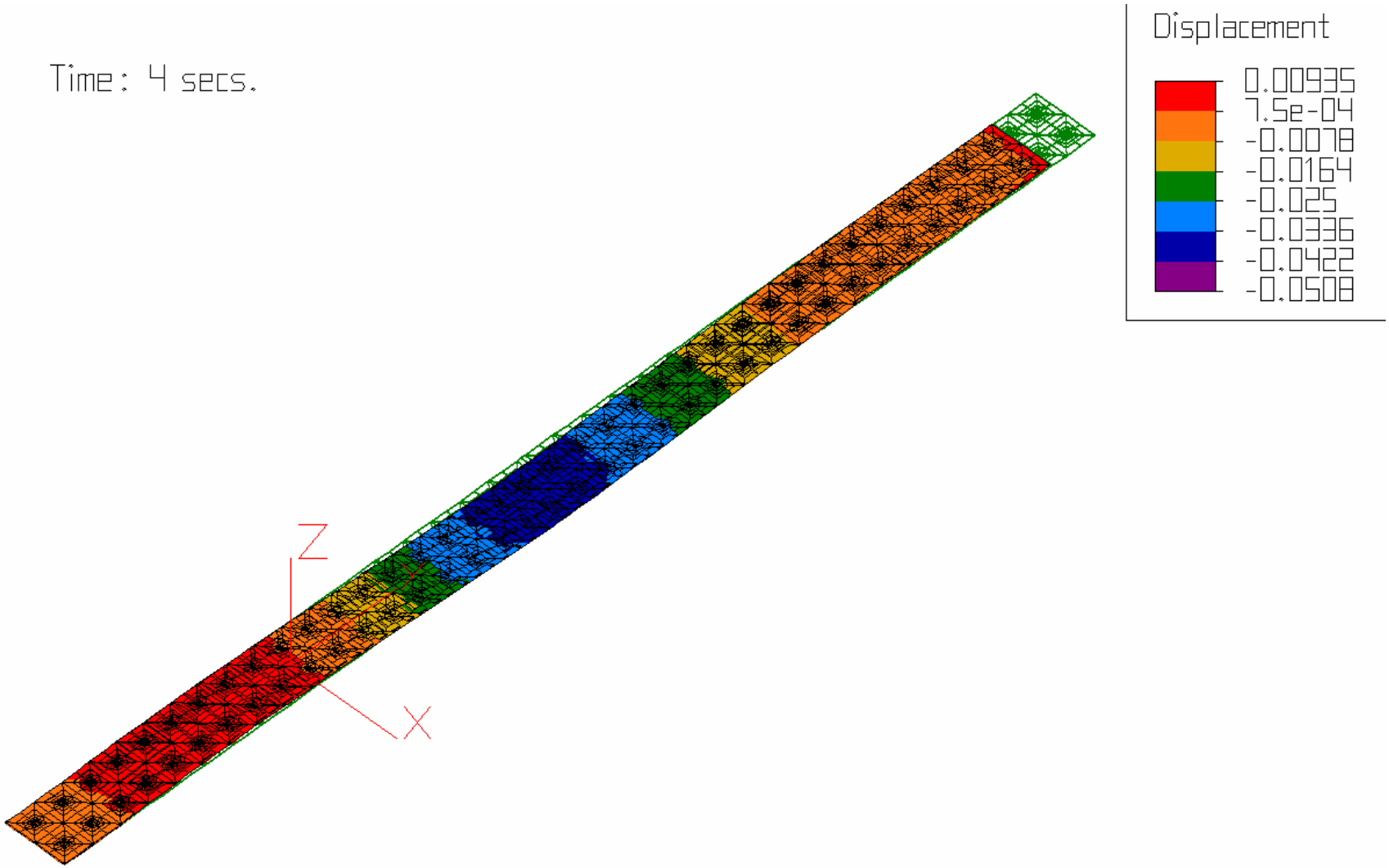
The model is based on 2CCD each of the half length.

When glue's E value is 1.4 N/mm^2





Out of plane displacement plots of the standard support case (2) Glue's E value is 14 N/mm^2



When glue's E value is 14 N/mm^2